

WHAT IS CLAIMED IS:

1. A module substrate mounting structure comprising:
a motherboard having connecting pads disposed on a surface thereof; and
a plurality of module substrates each having connecting terminals disposed on a surface thereof; wherein
said module substrates are stacked with a space therebetween on said motherboard, said connecting terminals of said module substrates are electrically connected to said connecting pads on said motherboard, a plurality of said connecting terminals are arranged along an edge portion of each of said module substrates, said module substrates are stacked with said connecting terminals aligned with each other, a plurality of said connecting pads are arranged on the surface of said motherboard in the direction of arrangement of said connecting terminals, a plurality of rows of said connecting pads are arranged to be sequentially offset from one another from inside of a region on said motherboard where said module substrates are mounted toward an outside thereof, said connecting terminals of an upper module substrate of said module substrates are electrically connected to a row of connecting pads on the outer side of a row of connecting pads connected to said connecting terminals of a lower module substrate via said connecting

2. A module substrate mounting structure according to Claim 1, wherein said module substrates have a nozzle suction area that is arranged to be drawn by a component-transporting suction nozzle.

4. A module substrate mounting structure according to Claim 1, wherein said module substrates have a converter power-supply circuit.

5. A module substrate mounting structure comprising:
a motherboard having connecting pads disposed on a
surface thereof; and
a plurality of module substrates each having connecting
terminals disposed on a surface thereof; wherein

said module substrates are stacked with a space therebetween on said motherboard, said connecting terminals of said module substrates are electrically connected to said connecting pad on said motherboard, a plurality of said connecting terminals are arranged along an edge portion of each of said module substrates, said module substrates are stacked on said motherboard and are sequentially offset from one another in the direction of arrangement of said connecting terminals so that said edge portions with said connecting terminals disposed thereon are aligned with one another, and said connecting pads to be electrically connected to said connecting terminals of said module substrates via said connecting members are located in the same row.

6. A module substrate mounting structure according to Claim 5, wherein a lower substrate recognition mark is located on a portion of said lower module substrate which is exposed as a result of said upper module substrate being arranged in an offset manner.

7. A module substrate mounting structure according to Claim 5, wherein said module substrates have a nozzle suction area that is arranged to be drawn by a component-transporting suction nozzle.

8. A module substrate mounting structure according to Claim 5, wherein a ratio of a length to a width of said module substrates is within a range of about 1/3 to about 1/1.

9. A module substrate mounting structure according to Claim 5, wherein said module substrates have a converter power-supply circuit.

10. A module substrate mounting structure comprising:
a motherboard having connecting pads disposed on a surface thereof; and

a plurality of module substrates each having connecting terminals disposed on a surface thereof; wherein

said module substrates are stacked with a space therebetween on said motherboard, said connecting terminals of said module substrates are electrically connected to said connecting pads on said motherboard, a plurality of said connecting terminals are arranged along an edge portion of each of said module substrates, said module substrates are stacked on said motherboard and are sequentially offset from one another in the direction of arrangement of said connecting terminals so that said edge portions with said connecting terminals disposed thereon are aligned with one

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another, a plurality of said connecting pads are arranged on the surface of said motherboard in the direction of arrangement of said connecting terminals, a plurality of rows of said connecting pads are arranged to be sequentially offset from one another from inside of a region on said motherboard where said module substrates are mounted toward an outside thereof, said connecting terminals of an upper module substrate of said module substrates are electrically connected to said row of connecting pads on the outer side of said row of connecting pads connected to said connecting terminals of a lower module substrate via said connecting members, and said connecting members connected to said upper module substrate project further than said connecting members connected to said lower module substrate.

11. A module substrate mounting structure according to Claim 10, wherein a lower substrate recognition mark is located on a portion of said lower module substrate which is exposed as a result of said upper module substrate being arranged in an offset manner.

12. A module substrate mounting structure according to Claim 10, wherein said module substrates have a nozzle suction area that is arranged to be drawn by a component-transporting suction nozzle.

13. A module substrate mounting structure according to Claim 10, wherein a ratio of a length to a width of said module substrates is within a range of about 1/3 to about 1/1.

14. A module substrate mounting structure according to Claim 10, wherein said module substrates have a converter power-supply circuit.

15. A module substrate mounting structure comprising:
a motherboard having connecting pads disposed on a surface thereof; and

a plurality of module substrates each having connecting terminals disposed on a surface thereof; wherein

said module substrates are stacked with a space therebetween on said motherboard, said connecting terminals of said module substrates are electrically connected to said connecting pads on said motherboard, a plurality of said connecting terminals are arranged along a pair of edge portions of each of said module substrates, and said module substrates are stacked with the space therebetween on said motherboard so that the directions of arrangement of said connecting terminals of said upper and lower module substrates are nearly perpendicular to each other.

FIG. 10

16. A module substrate mounting structure according to Claim 15, wherein said module substrates have a nozzle suction area that is arranged to be drawn by a component-transporting suction nozzle.

17. A module substrate mounting structure according to Claim 15, wherein a ratio of a length to a width of said module substrates is within a range of about 1/3 to about 1/1.

18. A module substrate mounting structure according to Claim 15, wherein said module substrates have a converter power-supply circuit.